

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

**Title of
Invention**

METHOD FOR FORMING INTERCONNECTS ON THIN WAFERS

Application Number :

Date :

First Named Applicant: Leonard J Gardecki

Attorney Docket Number: BUR920030026US1

TOTAL FEE AUTHORIZED \$ 934

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	750	750
Subtotal For Basic Filing Fees: \$ 750			

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 28	8	1202	18	144
Independent Claims : 3	0	1201	84	0
Subtotal For Extra Claims Fees: \$ 144				

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

AUTHORIZED BILLING INFORMATION**The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Deposit account number: 090456

Access Code *****

Deposit name: International Business Machines Corporation

Deposit authorized name: William D. Sabo

Signature: William D. Sabo/s/

Date (YYYYMMDD):

2003-06-13

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.